Adwill®
will give you the Advantage

300mm Fully-Automatic BG Tape Remover

RAD-3020F/12

Outline

–Fully-automatic BG Tape remover for single wafer.
–After the wafer is aligned, the back grinding tape is UV irradiated as necessary. Then the peeling tape is attached to the wafer periphery by heat seal method, and back grinding tape removal is performed.
–By using our unique wafer holding table and the new peeling method that reduces stress on the wafer, back grinding tape removal is performed without any contact with the wafer backside.
–By adopting the non-contact wafer backside handling method, contamination of wafer is prevented.

Option
•Host Communication Function(Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
•Compatible with clean room applications, and suitable for front-end process

Suitable Tapes
•BG Tape: Adwill E series, P series

Facility

Power Supply	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
	Power consumption	: 3.5kW (with UV Irradiation System: 10kW)
Air Supply	Air pressure	: 0.6-0.8MPa
	Air consumption	: >200L/min (ANR)
Vacuum Supply (for workpiece)	Vacuum pressure	: >-80kPa

Applicable Wafer Size

300mm
Please inquire about options for compatibility with specific wafer sizes.

Size

Width : 1,440mm
Depth : 2,105mm
Height : 1,800mm
(excluding the signal tower and protruding parts)

Weight

1,600kg

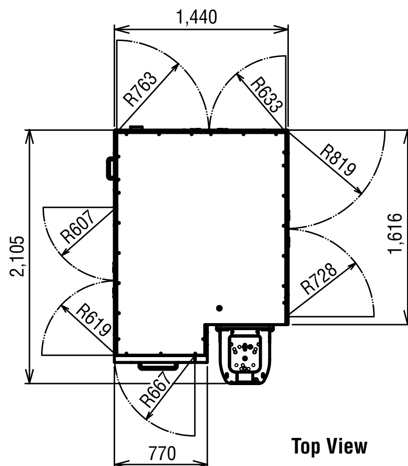
UPH

45wafers/hour

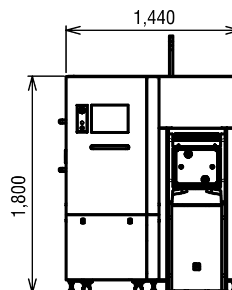
The above processing capacity is based on following conditions:
Wafer : 300mm diameter non-polished mirror wafer
Back grinding tape : E-6142S from LINTEC

External View

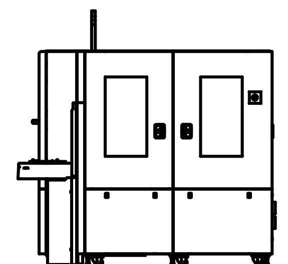
Unit:mm



Top View



Front View



Right Side View

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